# PRINTER, PRINTER HEAD, AND METHOD FOR FABRICATING PRINTER HEAD

ABSTRACT OF THE DISCLOSURE

A printer and a printer head employing a thermal inkjet method are disclosed. A heater element is arranged so as to overlie a wiring pattern layer carried by a semiconductor substrate, or a wiring pattern portion for power supplying or a wiring pattern portion for grounding, the wiring pattern portions being carried by a semiconductor substrate. This arrangement allows heat generated by the heater element to be efficiently transferred to a liquid ink chamber.

Figure 1